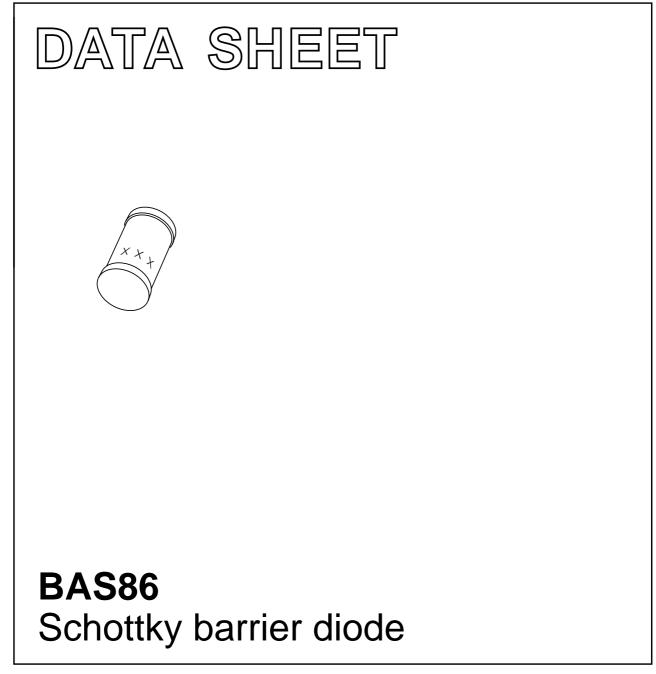
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1996 Mar 20 1996 Oct 01



#### **Product specification**

## Schottky barrier diode

# **BAS86**

### FEATURES

- Low forward voltage
- High breakdown voltage
- Guard ring protected
- Hermetically-sealed small SMD package.

### APPLICATIONS

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes.

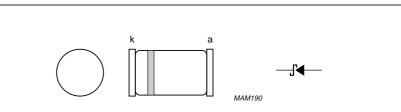
### DESCRIPTION

Planar Schottky barrier diode with an integrated protection ring against static discharges.

This surface mounted diode is

encapsulated in a hermetically sealed

SOD80C glass SMD package with tin-plated metal discs at each end. It is suitable for "automatic placement" and as such it can withstand immersion soldering.



Cathode indicated by a grey band.

Fig.1 Simplified outline (SOD80C), pin configuration and symbol.

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		_	50	V
l <sub>F</sub>	continuous forward current		_	200	mA
I <sub>F(AV)</sub>	average forward current	see Fig.2	_	200	mA
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1$ sec.; $\delta \le 0.5$	_	500	mA
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms		5	A
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	125	°C
T <sub>amb</sub>	operating ambient temperature		-65	+125	°C

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## ELECTRICAL CHARACTERISTICS

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	see Fig.3		
		I <sub>F</sub> = 0.1 mA	300	mV
		I <sub>F</sub> = 1 mA	380	mV
		I <sub>F</sub> = 10 mA	450	mV
		I <sub>F</sub> = 30 mA	600	mV
		I <sub>F</sub> = 100 mA	900	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 40 V; see Fig.4; note 1	5	μA
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 10$ mA to $I_R = 10$ mA; R <sub>L</sub> = 100 $\Omega$ ; measured at $I_R = 1$ mA; see Fig.6	4	ns
C <sub>d</sub>	diode capacitance	$f = 1 \text{ MHz}; V_R = 1 \text{ V}; \text{ see Fig.5}$	8	pF

### Note

1. Pulsed test:  $t_p$  = 300 µs;  $\delta$  = 0.02.

## THERMAL CHARACTERISTICS

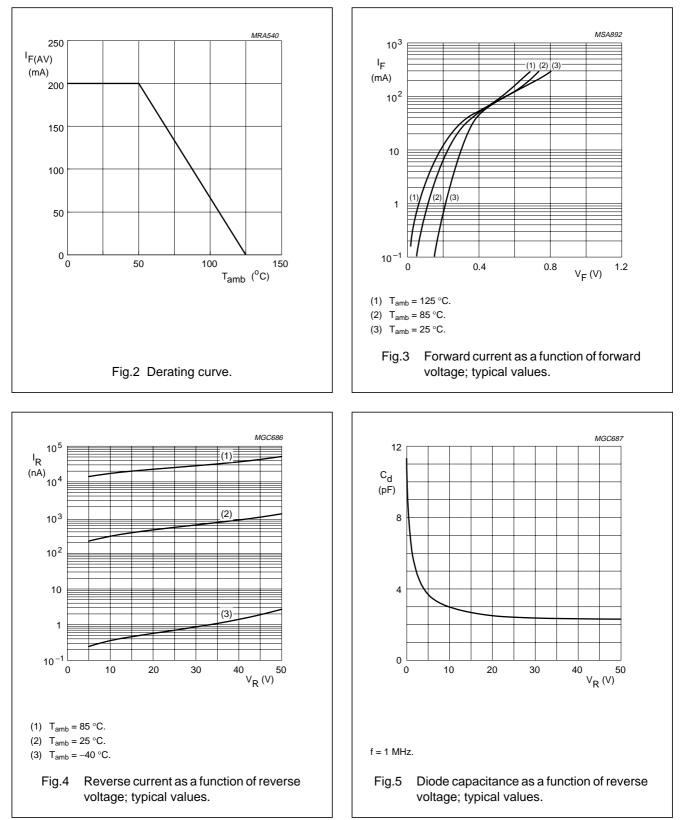
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	320	K/W

Note

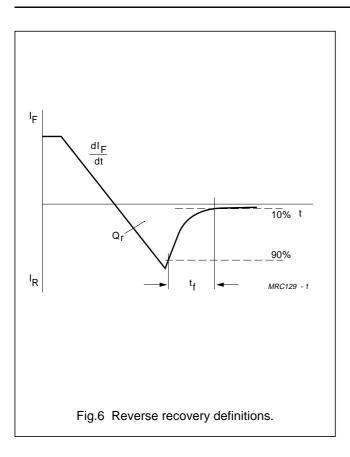
1. Refer to SOD80 standard mounting conditions.

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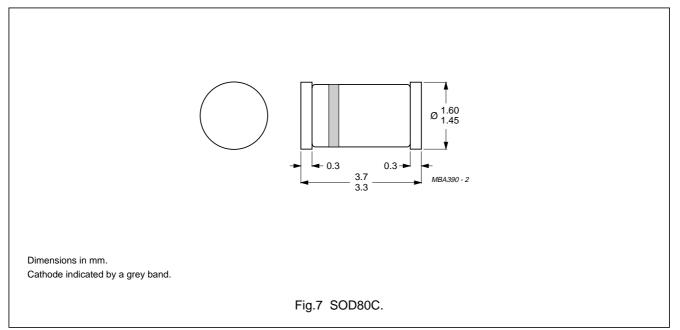


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### PACKAGE OUTLINE



#### DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.
Application information	
	ion is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.